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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

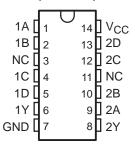
description/ordering information

These dual 4-input positive-AND gates are designed for 2-V to 5.5-V V_{CC} operation.

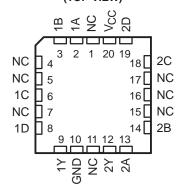
The 'LV21A devices perform the Boolean function $Y = A \bullet B \bullet C \bullet D$ or $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$ in positive logic.

These devices are fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

SN54LV21A . . . J OR W PACKAGE SN74LV21A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV21A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 B	Tube of 50	SN74LV21AD	11/04 A
	SOIC – D	Reel of 2500	SN74LV21ADR	LV21A
	SOP – NS	74LV21A		
4000 +- 0500	SSOP – DB	Reel of 2000	SN74LV21ADBR	LV21A
–40°C to 85°C		Tube of 90	SN74LV21APW	
	TSSOP - PW	Reel of 2000	SN74LV21APWR	LV21A
		Reel of 250	SN74LV21APWT	
	TVSOP – DGV	Reel of 2000	SN74LV21ADGVR	LV21A
	CDIP – J	Tube of 25	SNJ54LV21AJ	SNJ54LV21AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV21AW	SNJ54LV21AW
	LCCC – FK	Tube of 55	SNJ54LV21AFK	SNJ54LV21AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each gate)

	INP		OUTPUT	
Α	В	С	D	Y
Н	Н	Н	Н	Н
L	X	X	X	L
X	L	Χ	Χ	L
Х	Χ	L	Χ	L
Х	Χ	Χ	L	L

logic diagram (positive logic)





Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		0.5 V to 7 V
Output voltage range applied in high or low sta	te, V _O (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range applied in power-off state	e, VO (see Note 1)	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0)		–20 mA
Output clamp current, I_{OK} ($V_O < 0$)		–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 3)		
•	DB package	96°C/W
	DGV package	127°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			SN54L\	/21A	SN74L	UNIT		
			MIN	MAX	MIN	MAX	UNII	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
V	High level innerticate as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		$V_{CC} \times 0.7$		V	
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$			
		V _{CC} = 2 V		0.5		0.5		
V.	Low level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V	$CC \times 0.3$	\	CC×0.3	V	
V _{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	V	$CC \times 0.3$	\	CC×0.3	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		V _{CC} × 0.3		V _{CC} × 0.3		
٧ı	Input voltage		0,0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	VCC	V	
		V _{CC} = 2 V	N. C.	-50		-50	μΑ	
	High lovel output output	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2		
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12		
		V _{CC} = 2 V		50		50	μΑ	
	Low lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2		
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6	6		mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200		
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20		
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		T	SN54LV21A	SN74LV21A		
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX	MIN TYP MAX	UNIT	
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1	V _{CC} -0.1		
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2	2	V	
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	2.48	V	
	I _{OH} = -12 mA	4.5 V	3.8	3.8		
	I _{OL} = 50 μA	2 V to 5.5 V	0.1	0.1		
V	I _{OL} = 2 mA	2.3 V	0.4	0.4	V	
VOL	I _{OL} = 6 mA	3 V	0.44	0.44	V	
	I _{OL} = 12 mA	4.5 V	0.55	0.55		
lį	V _I = 5.5 V or GND	0 to 5.5 V	±1	±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20	20	μΑ	
l _{off}	V_I or $V_O = 0$ to 5.5 V	0	5	5	μΑ	
Ci	V _I = V _{CC} or GND	3.3 V	1.9	1.9	pF	

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

FROM		то	LOAD	T _A = 25°C			SN54LV21A	SN74LV21A		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
t _{pd}	A, B, C, or D	Υ	C _L = 15 pF		7*	12*	1* 14*	1	14	ns
^t pd	A, B, C, or D	Υ	C _L = 50 pF		9.2	15.7	1 19	1	19	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T _A = 25°C			SN54LV21A		SN74LV21A		LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{pd}	A, B, C, or D	Υ	C _L = 15 pF		5.1*	7*	19	8.5*	1	8.5	ns
t _{pd}	A, B, C, or D	Υ	C _L = 50 pF		6.6	10.5	Q1	12	1	12	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD CAPACITANCE	T _A = 25°C			SN54LV21A	SN74LV21A		LINUT
PARAMETER	(INPUT)	(OUTPUT)		MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
t _{pd}	A, B, C, or D	Υ	C _L = 15 pF		3.8*	5*	1* 6*	1	6	ns
t _{pd}	A, B, C, or D	Υ	C _L = 50 pF		4.9	7	Q 1 8	1	8	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 5)

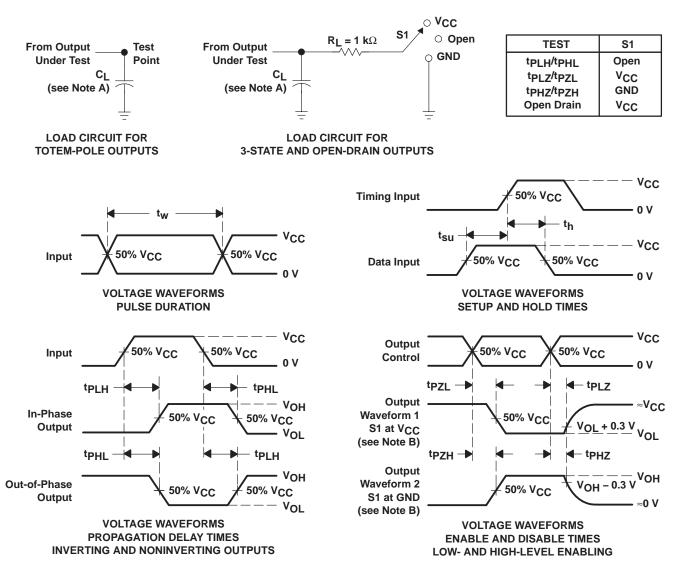
	DADAMETED	SN	LINUT		
	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		0	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.2		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	VCC	TYP	UNIT
<u> </u>	Dougs dissipation appositance	C. F0 nF	f 40 MH-	3.3 V	17.4	PF
Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},$	f = 10 MHz	5 V	20.2	рг

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpZL and tpZH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV21AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21ADGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV21A	Samples
SN74LV21APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples
SN74LV21APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

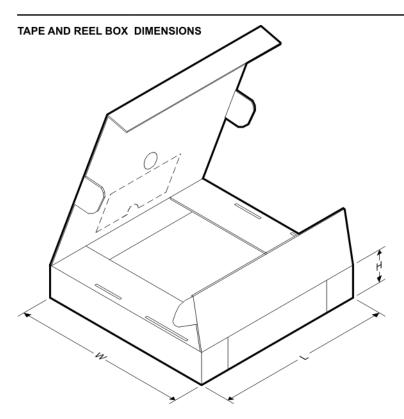
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

"All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV21ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV21ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV21ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV21ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV21APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

All difficultions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV21ADBR	SSOP	DB	14	2000	853.0	449.0	35.0
SN74LV21ADGVR	TVSOP	DGV	14	2000	853.0	449.0	35.0
SN74LV21ADR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LV21ANSR	SO	NS	14	2000	853.0	449.0	35.0
SN74LV21APWR	TSSOP	PW	14	2000	853.0	449.0	35.0

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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